

IN THE CLAIMS

Please amend the claims as follows:

Claims 1-5 (Canceled).

Claim 6 (New): An optical waveguide chip comprising:

a core portion as an optical waveguide;

a clad portion formed around the core portion; and

an optical fiber guide portion for positioning an optical fiber which is to be connected with the core portion,

wherein the core portion, the clad portion, and the optical fiber guide portion are composed of a cured radiation-sensitive polysiloxane composition, and have been formed by alkali developing.

Claim 7 (New): The optical waveguide chip according to Claim 6, wherein the optical waveguide chip is for being connected with a single-mode optical fiber.

Claim 8 (New): The optical waveguide chip according to Claim 6, wherein the optical waveguide chip has an optical filter insertion hole for being inserted with an optical filter which is to be disposed intersecting with the core portion.

Claim 9 (New): An optical component, comprising a dielectric multilayer filter which has been inserted and fixed in the optical filter insertion hole of the optical waveguide chip according to Claim 8.

Claim 10 (New): A method for manufacturing the optical waveguide chip according to Claim 6, wherein alkali developing is performed during patterning of the core portion, the clad portion, and the optical fiber guide portion.

Claim 11 (New): The method for manufacturing the optical waveguide chip according to Claim 7, wherein alkali developing is performed during patterning of the core portion, the clad portion, and the optical fiber guide portion.